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**MMDT4413** 

#### **COMPLEMENTARY PAIR SMALL SIGNAL TRANSISTOR IN SOT363**

#### **Features**

- Epitaxial Die Construction
- Two Internally Isolated NPN/PNP Transistors in One Package NPN = 4401

PNP = 4403

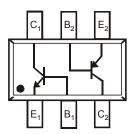
- Ideal for Medium Power Amplification and Switching
- Ultra-Small Surface Mount Package
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT363
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Finish. Solderable per MIL-STD-202, Method 208 <sup>3</sup>
- Weight: 0.006 grams (approximate)



Top View



Device Schematic Top View

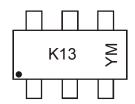
#### Ordering Information (Note 4)

Part Number	Marking	Reel Size (inches)	Tape Width (mm)	Quantity per Reel
MMDT4413-7-F	K13	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**



K13= Product Type Marking Code YM = Date Code Marking Y = Year (ex: A = 2013) M = Month (ex: 9 = September)

Date Code Key

Year	2010	201	11	2012	20	013	2014	2	2015	2016		2017
Code	Х	Y		Z		A	В		С	D		Е
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D



# Absolute Maximum Ratings: NPN, 4401 Type (Q<sub>1</sub>) (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	60	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6	V
Collector Current	Ic	600	mA

#### Absolute Maximum Ratings: PNP, 4403 Type (Q2) (@TA = +25°C unless otherwise specified.)

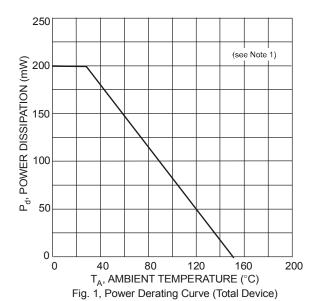
Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-40	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	V
Emitter-Base Voltage	V <sub>EBO</sub>	-5	V
Collector Current	Ic	-600	mA

#### Thermal Characteristics – Total Device (@TA = +25°C unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5) Total Device	P <sub>D</sub>	200	mW
Thermal Resistance, Junction to Ambient (Note 5)	$R_{ hetaJA}$	625	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

Note:

#### **Thermal Characteristics - Total Device**



<sup>5.</sup> For a device mounted on minimum recommended pad layout with 1oz copper that is on a single-sided 1.6mm FR4 PCB; the device is measured under still air conditions whilst operating in a steady-state.

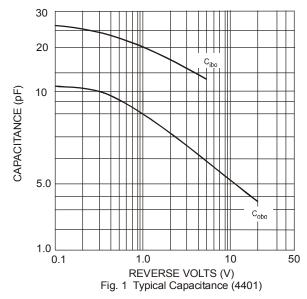


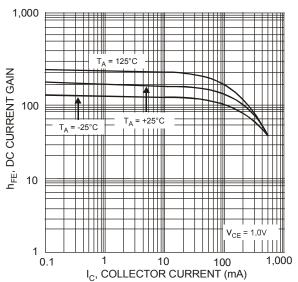
### Electrical Characteristics, NPN 4401 Section (@T<sub>A</sub> = +25°C unless otherwise specified.)

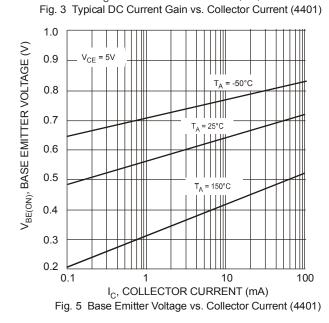
Characteristic	Symbol	Min	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 6)					
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	60	_	V	$I_C = 100 \mu A, I_E = 0$
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	40		V	I <sub>C</sub> = 1.0mA, I <sub>B</sub> = 0
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6.0		V	I <sub>E</sub> = 100 μA, I <sub>C</sub> = 0
Collector Cutoff Current	I <sub>CEX</sub>	_	100	nA	V <sub>CE</sub> = 35V, V <sub>EB(OFF)</sub> = 0.4V
Base Cutoff Current	I <sub>BL</sub>	_	100	nA	V <sub>CE</sub> = 35V, V <sub>EB(OFF)</sub> = 0.4V
ON CHARACTERISTICS (Note 6)			•	•	
DC Current Gain	h <sub>FE</sub>	20 40 80 100 40	  300 	_	$I_{C} = 100 \mu A, V_{CE} = 1.0 V$ $I_{C} = 1.0 m A, V_{CE} = 1.0 V$ $I_{C} = 10 m A, V_{CE} = 1.0 V$ $I_{C} = 150 m A, V_{CE} = 1.0 V$ $I_{C} = 500 m A, V_{CE} = 2.0 V$
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	0.40 0.75	V	$I_C$ = 150mA, $I_B$ = 15mA $I_C$ = 500mA, $I_B$ = 50mA
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	0.75 —	0.95 1.2	V	I <sub>C</sub> = 150mA, I <sub>B</sub> = 15mA I <sub>C</sub> = 500mA, I <sub>B</sub> = 50mA
SMALL SIGNAL CHARACTERISTICS					
Output Capacitance	C <sub>cb</sub>	_	6.5	pF	$V_{CB} = 5.0V$ , $f = 1.0MHz$ , $I_E = 0$
Input Capacitance	C <sub>eb</sub>	_	30	pF	$V_{EB} = 0.5V$ , $f = 1.0MHz$ , $I_C = 0$
Input Impedance	h <sub>ie</sub>	1.0	15	kΩ	
Voltage Feedback Ratio	h <sub>re</sub>	0.1	8.0	x 10 <sup>-4</sup>	$V_{CE} = 10V, I_{C} = 1.0 \text{mA}, f = 1.0 \text{kHz}$
Small Signal Current Gain	h <sub>fe</sub>	40	500	_	VCE - 10V, IC - 1.0IIIA, I - 1.0KHZ
Output Admittance	h <sub>oe</sub>	1.0	30	μS	
Current Gain-Bandwidth Product	f⊤	250	_	MHz	$V_{CE} = 10V, I_{C} = 20mA,$ f = 100MHz
SWITCHING CHARACTERISTICS					
Delay Time	t <sub>d</sub>		15	ns	$V_{CC} = 30V, I_{C} = 150mA,$
Rise Time	t <sub>r</sub>	_	20	ns	$V_{BE(off)} = 2.0V, I_{B1} = 15mA$
Storage Time	ts	_	225	ns	V <sub>CC</sub> = 30V, I <sub>C</sub> = 150mA,
Fall Time	t <sub>f</sub>	_	30	ns	$I_{B1} = I_{B2} = 15mA$

Note: 6. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%









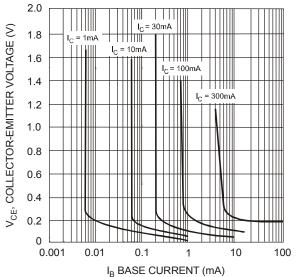


Fig. 2 Typical Collector Saturation Region (4401)

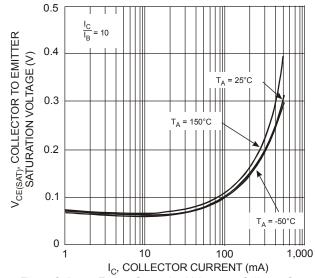


Fig. 4 Collector Emitter Saturation Voltage vs. Collector Current (4401)

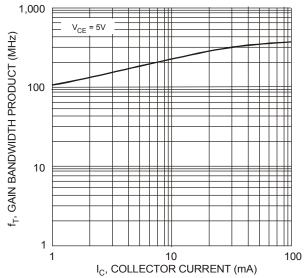


Fig. 6 Gain Bandwidth Product vs. Collector Current (4401)

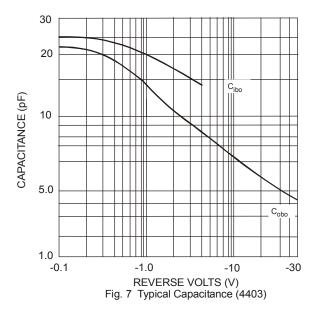


## Electrical Characteristics, PNP 4403 Section (@T<sub>A</sub> = +25°C unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition		
OFF CHARACTERISTICS (Note 6)							
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-40		V	$I_C = -100\mu A, I_E = 0$		
Collector-Emitter Breakdown Voltage	BV <sub>CEO</sub>	-40		V	$I_C = -1.0 \text{mA}, I_B = 0$		
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-5.0		V	$I_E = -100\mu A, I_C = 0$		
Collector Cutoff Current	I <sub>CEX</sub>	_	-100	nA	V <sub>CE</sub> = -35V, V <sub>EB(OFF)</sub> = -0.4V		
Base Cutoff Current	I <sub>BL</sub>	_	-100	nA	V <sub>CE</sub> = -35V, V <sub>EB(OFF)</sub> = -0.4V		
ON CHARACTERISTICS (Note 6)							
DC Current Gain	h <sub>FE</sub>	30 60 100 100 20	  300 	_	$I_{C} = -100\mu A, V_{CE} = -1.0V$ $I_{C} = -1.0mA, V_{CE} = -1.0V$ $I_{C} = -10mA, V_{CE} = -1.0V$ $I_{C} = -150mA, V_{CE} = -2.0V$ $I_{C} = -500mA, V_{CE} = -2.0V$		
Collector-Emitter Saturation Voltage	V <sub>CE(SAT)</sub>	_	-0.40 -0.75	V	$I_C$ = -150mA, $I_B$ = -15mA $I_C$ = -500mA, $I_B$ = -50mA		
Base-Emitter Saturation Voltage	V <sub>BE(SAT)</sub>	-0.75 —	-0.95 -1.30	V	$I_C = -150 \text{mA}, I_B = -15 \text{mA}$ $I_C = -500 \text{mA}, I_B = -50 \text{mA}$		
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	C <sub>cb</sub>	_	8.5	pF	$V_{CB} = -10V$ , $f = 1.0MHz$ , $I_E = 0$		
Input Capacitance	C <sub>eb</sub>	_	30	pF	$V_{EB} = -0.5V$ , $f = 1.0MHz$ , $I_{C} = 0$		
Input Impedance	h <sub>ie</sub>	1.5	15	kΩ			
Voltage Feedback Ratio	h <sub>re</sub>	0.1	8.0	x 10 <sup>-4</sup>	V <sub>CF</sub> = -10V, I <sub>C</sub> = -1.0mA, f = 1.0kHz		
Small Signal Current Gain	h <sub>fe</sub>	60	500	_	VCE10V, IC1.0ITIA, I - 1.0KHZ		
Output Admittance	h <sub>oe</sub>	1.0	100	μS			
Current Gain-Bandwidth Product	f⊤	200	_	MHz	$V_{CE} = -10V, I_{C} = -20mA, f = 100MHz$		
SWITCHING CHARACTERISTICS							
Delay Time	t <sub>d</sub>	_	15	ns	$V_{CC} = -30V, I_{C} = -150mA,$		
Rise Time	t <sub>r</sub>	_	20	ns	$V_{BE(off)} = -2.0V, I_{B1} = -15mA$		
Storage Time	ts	_	225	ns	V <sub>CC</sub> = -30V, I <sub>C</sub> = -150mA,		
Fall Time	t <sub>f</sub>	_	30	ns	$I_{B1} = I_{B2} = -15\text{mA}$		

Note: 6. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%





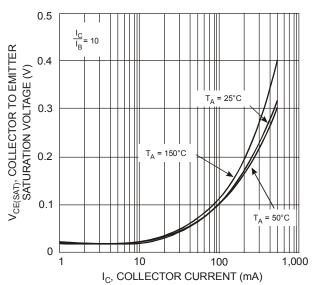


Fig. 9 Collector Emitter Saturation Voltage vs. Collector Current (4403)

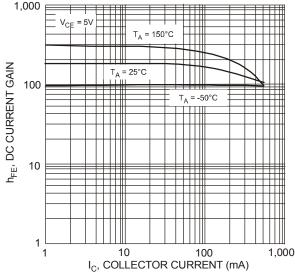


Fig. 11 DC Current Gain vs. Collector Current (4403)

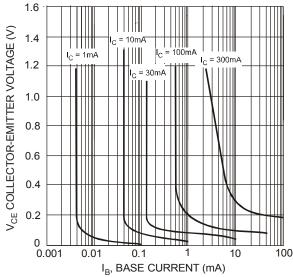


Fig. 8 Typical Collector Saturation Region (4403)

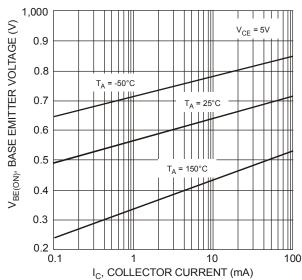
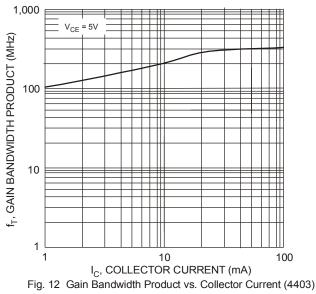


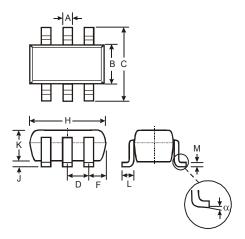
Fig. 10 Base-Emitter Voltage vs. Collector Current (4403)





### **Package Outline Dimensions**

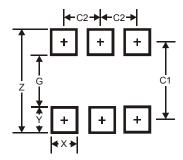
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



	SOT363							
Dim	Min	Min Max						
Α	0.10	0.30	0.25					
В	1.15	1.35	1.30					
С	2.00	2.20	2.10					
D		0.65 Typ						
F	0.40	0.425						
Н	1.80	2.20	2.15					
J	0	0.10	0.05					
K	0.90	1.00	1.00					
L	0.25 0.40 0.30							
М	0.10	0.22	0.11					
α	0°	8°	-					
All	All Dimensions in mm							

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C1	1.9
C2	0.65



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